



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134 Tel: (408) 943-2600

## PRODUCT CHANGE NOTIFICATION

**PCN:** PCN155363

**Date:** February 20, 2015

**Subject:** Qualification of the New 256Kb and 128Kb SPI and I2C F-RAM Product Series

**To:** PCN ADMIN  
CYPRESS  
pcn\_admin@cypress.com

**Change Type:** Major

### Description of Change:

Cypress is pleased to announce the qualification of the new 256Kb and 128Kb Serial Peripheral Interface (SPI) and Inter-Integrated Circuit (I2C) interface F-RAM product series.

Cypress will be discontinuing the existing 256Kb and 128Kb SPI and I2C F-RAM product series. The list of affected part numbers with replacement part numbers, Last Time Buy (LTB) and Last Time Ship (LTS) dates are provided in an attachment to this notification. The new products are drop-in, form, fit, function and pin-to-pin compatible with the existing parts.

New datasheets have been issued for the new part numbers. Datasheets for both the old and the new part numbers can be downloaded from the Cypress web site at [www.cypress.com/nonvolatile/](http://www.cypress.com/nonvolatile/) by clicking on the "Datasheets" link in the "Related Documentation" section on the right-hand side of the webpage. The new Datasheets are attached to this notification. The differences between the old and new datasheets are outlined in the attached Knowledge-Based Articles (KBA).

The new industrial-grade 256Kb and 128Kb SPI and I2C F-RAM product series will be qualified with Copper Palladium (CuPd) or Gold (Au) wire bonds. Devices with CuPd wire bonds will have a "C" top-marked in the lower right hand corner of the device.

The new industrial-grade 256Kb and 128Kb SPI and I2C F-RAM product series will have an additional top passivation layer and packaged parts will be rated as Moisture Sensitive Level (MSL) 3.

**Benefit of Change:**

The new products will provide a higher level of quality and reliability.

**Affected Part Numbers:** 10

**Affected Parts:** Refer to attached 'Affected Parts List' file

**Qualification Status:**

The new products and the CuPd wire bonds have been qualified through a series of tests documented in the Qualification Test Plan (QTP) reports listed in the table below. The QTP reports can be found as attachments to this notification or by visiting [www.cypress.com](http://www.cypress.com) and typing the QTP number into the keyword search window.

Qualification Description	QTP Number
CML 8-SOIC with Au Wire	142801
UTAC 8-SOIC with CuPd Wire	142502
UTAC 8-DFN with CuPd Wire	142503
256Kb/128Kb Industrial Die	141603

**Sample Status:**

Samples for the replacement products listed in the attached "Affected Part Numbers" file are available now. Please contact your sales representative as soon as possible and no later than 30 days from this notification to place sample orders.

**Approximate Implementation Date:**

The new products are available with the date of this notification. The previous 256Kb and 128Kb SPI and I2C F-RAM products listed under the "Affected Part Number" column in the attachment are subject to End of Life (EOL) with the Last Time Buy (LTB) and Last Time Ship (LTS) dates.

**Anticipated Impact:**

The new products are drop-in, form, fit, function and pin-to-pin compatible with the existing parts.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

**Method of Identification:**

Cypress maintains traceability of our products to the wafer level, including wafer fabrication location, through the lot number marked on the package.

**Response Required:**

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at [pcn\\_adm@cypress.com](mailto:pcn_adm@cypress.com).

Sincerely,  
Cypress PCN Administration